

# PRODUCT / PROCESS CHANGE INFORMATION

## 1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/23/13938	
1.3 Title of PCI	AMKOR ATP (Philippines) CHANGE OF CARRIER TAPE SUPPLIER (Wi 16mm BGA 8x8) for TFBGA 8x8 100L products	
1.4 Product Category	STM32G4x, STM32H7x, STM32F7x, assembled in BGA 8x8 package	
1.5 Issue date	2023-05-16	

## 2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

## 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Boxes, trays, carriers, back grinding tape, wafer mounting tape, mold tape, etc..	AMKOR ATP (Philippines)

## 4. Description of change

	Old	New
4.1 Description	Current ST material code reference: - SID# 201305988 (CARRIER TAPE Wi 16mm BGA 8x8) supplied by PEAK	Change of supplier for ST material code reference: - SID# 201309188 (CARRIER TAPE Wi 16mm BGA 8x8) supplied by C-PAK
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on the commercial product	

## 5. Reason / motivation for change

5.1 Motivation	Current supplier Peak will discontinue carrier tape SID# 201305988
5.2 Customer Benefit	SERVICE IMPROVEMENT

## 6. Marking of parts / traceability of change

6.1 Description	ST traceability ensured by ST internal tools.
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## 7. Timing / schedule

7.1 Date of qualification results	2023-05-03
7.2 Intended start of delivery	2023-06-26
7.3 Qualification sample available?	Not Applicable

## 8. Qualification / Validation

8.1 Description	13938 MDG-GPM-qualification.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-05-16

9. Attachments (additional documentations)		
13938 Public product.pdf 13938 MDG-GPM-qualification.pdf		

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F745VEH6	
	STM32F765VGH6	
	STM32G473VEH6	
	STM32H743VIH6	



## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

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**PCI Reference :** MDG/23/13938

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32G473VEH6	STM32F745VEH6TR	STM32F765VGH6
STM32F765VGH6TR	STM32H743VIH6	STM32F745VEH6
STM32G473VEH6TR	STM32H743VIH6TR	STM32H742VIH6
STM32H742VIH6TR		

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